## **HR02 Series**

## **High Reliability Resistors**





#### **GENERAL DESCRIPTION**

The HR Series is the next generation of surface mount High Value Resistors. This product was designed with our proprietary Glass Sandwich FLEXITERM® Technology. The FLEXITERM® is a surface mountable automotive and medically qualified termination that adds an extra margin against damage due to flexture during installation. The HR Series has been designed with high quality selected materials that yield excellent performance in a small size. Resistor is designed to be embedded in glass sandwich to avoid environmental conditions, and provide low burst noise at high thin film resistance values. This product is ideal for use in applications requiring surface mountable small outline EIA resistors.

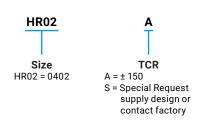
#### **FEATURES**

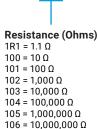
- EIA 0402 Size
- Power Rating: 125 mW
- Low Current Consumption
- High Voltage
- Operating Temperature -40°C to +125°C
- Low Burst Noise

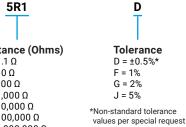
### **APPLICATIONS**

- · Multi Chip Module (MCM)
- Bias Networks
- Test and Measurement Equipment
- Aerospace
- Medical
- Automotive

#### **HOW TO ORDER**







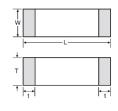




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## MECHANICAL DIMENSIONS mm (inches)

Length	1.00±0.10	
(L)	(0.039±0.004)	
Width	0.50±0.10	
(W)	(0.020±0.004)	
Thickness	0.50±0.10	
(T)	(0.020±0.004)	
Terminal	0.25±0.15	
(t)	(0.010±0.006)	



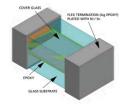
## 0402 TYPICAL CHARACTERISTICS

Resistor	Detail	
Outline	EIA 0402	
Package	Glass wafer sandwich	
Termination	FLEXITERM® (Ag/Epoxy), plated	
Power Rating	125 mW	
Operating Temperature Range	-40°C to +125°C	

Resistors from 1k to 30M Ohms available upon request

### **STANDARD VALUES**

Part Number	Value (ohm)	
HR02A102FZTR	1000	
HR02A222FZTR	2200	
HR02A472FZTR	4700	
HR02A103FZTR	10000	
HR02A223FZTR	22000	
HR02A473FZTR	47000	
HR02A104FZTR	100000	
HR02A224FZTR	220000	
HR02A474FZTR	470000	
HR02A105FZTR	1000000	
HR02A225FZTR	2200000	
HR02A475FZTR	4700000	
HR02A106FZTR	10000000	
HR02A226FZTR	22000000	
HR02A306FZTR	30000000	

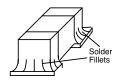


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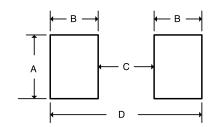


#### SUGGESTED MOUNTING PAD DIMENSIONS



**Normal Pads** 

W = Chip Width L = Chip Length T = Chip Thickness



Case Size	A Min.	B Min.	C Min.	D Min.
0402	0.54 (0.0213)	0.3175 (0.0125)	0.523 (0.0206)	1.107 (0.0436)

mm (inches)

#### NOTES:

Mounting will allow the solder fillet to travel up approximately 0.015" of the chip's end and side termination surface. Heavier fillets require a predeposition of solder paste and or an increase in pad dimensions. Typical solder paste application is a .008" to 0.01" thickness with >50% of volume in solder alloy. Can be mounted in both vertical and horizontal orientation without changing electrical performance

### **POWER DERATING**

# **Power Derating Curve** 150 Rated Power [mW] 100 50 0 -50 0 50 100 150 Ambient Temperature [°C]